

What is claimed is:

1. A semiconductor die package comprising:

a polymer base comprising a lower surface and an upper surface, the upper surface for mounting at least one semiconductor die;

a polymer cap operatively secured over at least a portion of the upper surface of the base forming a cavity, the cap having a light transmissive member operatively positioned to allow light of predetermined wavelengths to pass between at least a portion of the upper surface of the base and the light transmissive member; and

a plurality of conductive leads extending through the base from the lower surface of the base to the cavity.

2. A matrix of semiconductor die packages comprising:

a base matrix comprising a plurality of polymer bases, each base comprising a surface for mounting at least one semiconductor die;

a cap matrix comprising a plurality of polymer caps operatively secured over the base matrix, each base and cap combination forming a cavity, each cap having a light transmissive member operatively positioned to allow light of predetermined wavelengths to pass between the surface for mounting at least one semiconductor die of a corresponding base and the light transmissive member; and

a plurality of conductive leads extending through each base from an outside surface of each base to the corresponding cavity formed by each cap and base combination.

3. A method of making a semiconductor die package comprising:

forming a polymer base comprising a lower surface and an upper surface, the upper surface for mounting at least one semiconductor die;

forming a polymer cap operatively secured over at least a portion of the upper surface of the base forming a cavity, the cap having a light transmissive member operatively positioned to allow light of predetermined wavelengths to pass between at least a portion of the upper surface of the base and the light transmissive member; and

forming a plurality of conductive leads extending through the base from the lower surface of the base to the cavity.

4. A method of making semiconductor die packages comprising:

forming a base matrix comprising a plurality of polymer bases, each base comprising a surface for mounting at least one semiconductor die;

forming a cap matrix comprising a plurality of polymer caps operatively secured over the base matrix, each base and cap combination forming a cavity, each cap having a light transmissive member operatively positioned to allow light of predetermined wavelengths to pass between the surface for mounting at least one semiconductor die of a corresponding base and the light transmissive member; and

positioning a plurality of conductive leads extending through each base from an outside surface of each base to the corresponding cavity formed by each cap and base combination.